

Specification of Thermoelectric Module

TES1-01728

Description

The 17 couples, 12mm × 12mm size module is a single stage module which is made of our high performance ingot to achieve superior cooling performance and 70°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

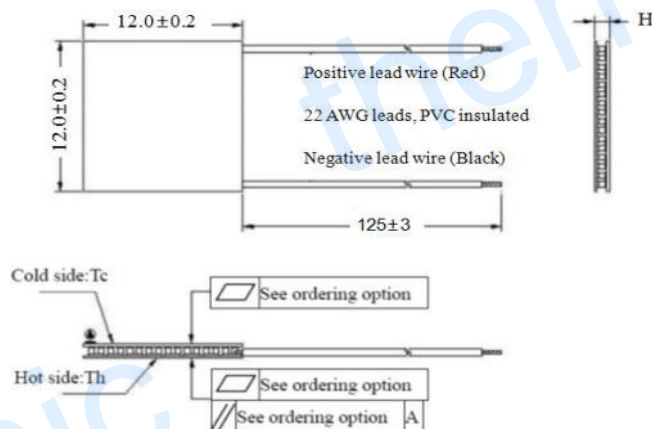
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

| | | | |
|----------------------------|------|------|---|
| Th (°C) | 27 | 50 | Hot side temperature at environment: dry air, N ₂ |
| DT _{max} (°C) | 70 | 79 | Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side |
| U _{max} (Voltage) | 2.11 | 2.27 | Voltage applied to the module at DT _{max} |
| I _{max} (Amps) | 2.76 | 2.76 | DC current through the modules at DT _{max} |
| Q _{Cmax} (Watts) | 3.76 | 4.05 | Cooling capacity at cold side of the module under DT=0 °C |
| AC resistance (Ohms) | 0.58 | 0.62 | The module resistance is tested under AC |
| Tolerance (%) | ± 10 | | For thermal and electricity parameters |

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

1. T100: BiSn (T_{melt}=138°C)
2. T200: CuAgSn (T_{melt} = 217°C)
3. T240: SbSn (T_{melt} = 240°C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

Ordering Option

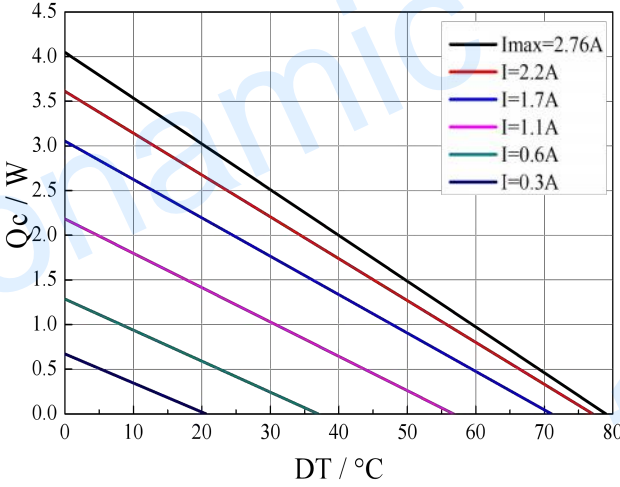
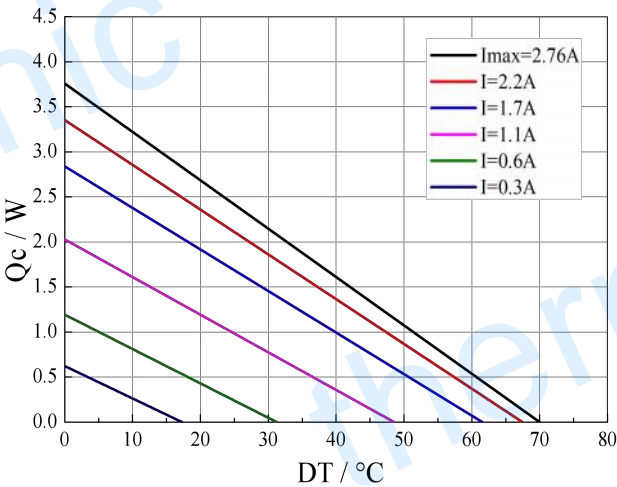
| Suffix | Thickness H (mm) | Flatness/ Parallelism (mm)Parallelism (mm) | Lead wire length(mm)Standard/Optional length |
|--------|------------------|--|--|
| TF | 0: 4.2 ± 0.1 | 0: 0.05/0.05 | 125±3/Specify |
| TF | 1: 4.2 ± 0.03 | 1: 0.02/0.02 | 125±3/Specify |

Eg. TF01: Thickness 4.2 ± 0.1 (mm) and Flatness 0.02/0.02 (mm)

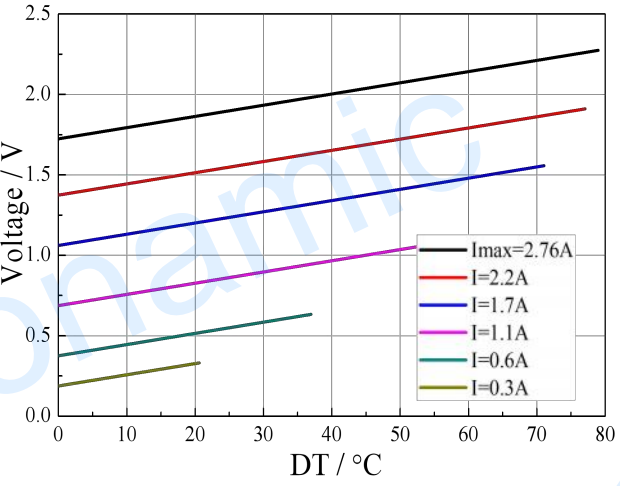
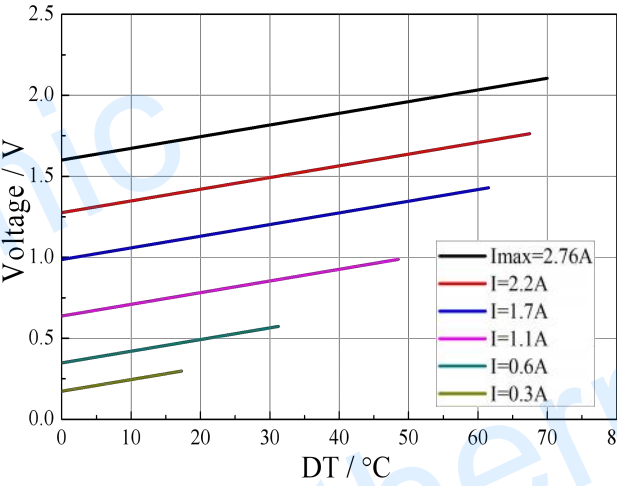
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Performance Curves at Th=27 °C

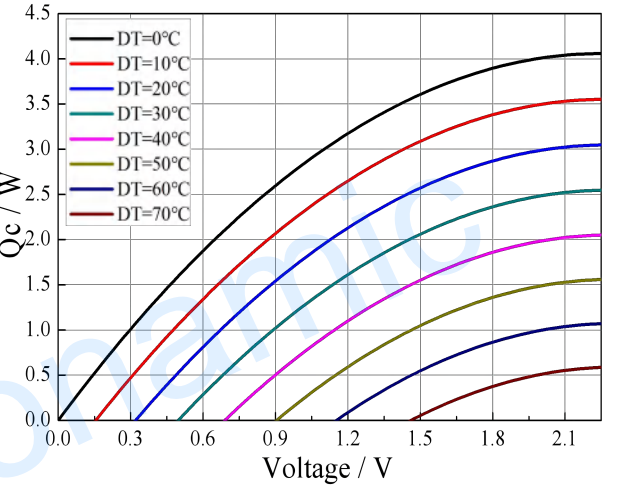
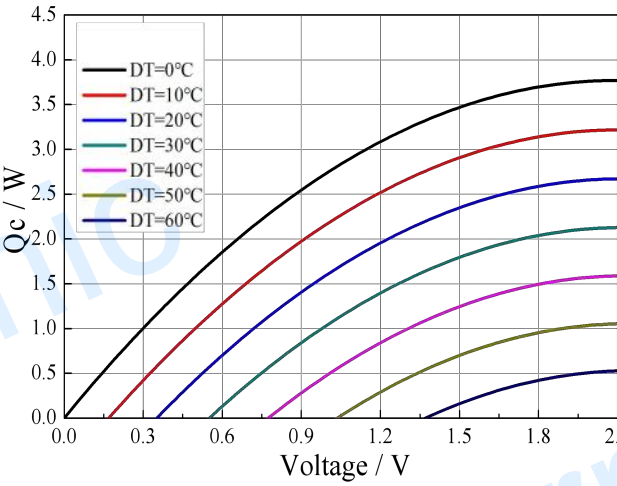
Performance Curves at Th=50 °C



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(DT)$

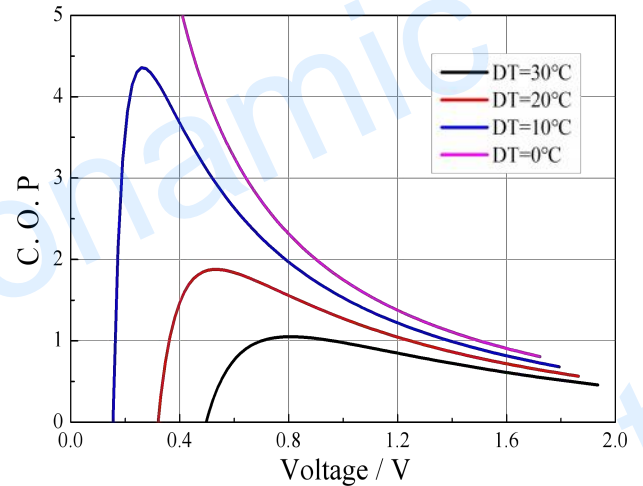
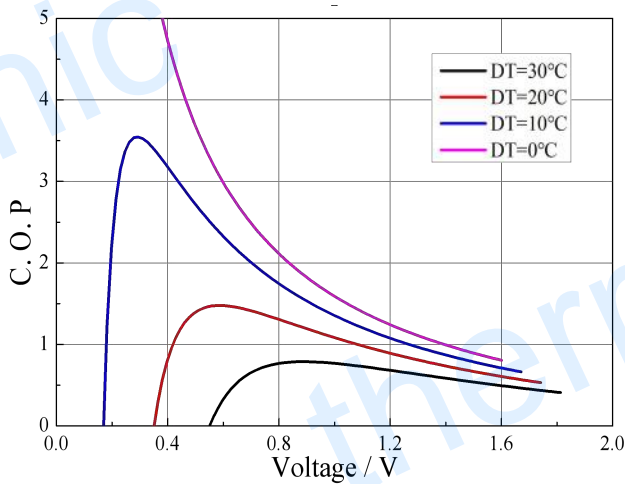


Standard Performance Graph $Q_c = f(V)$

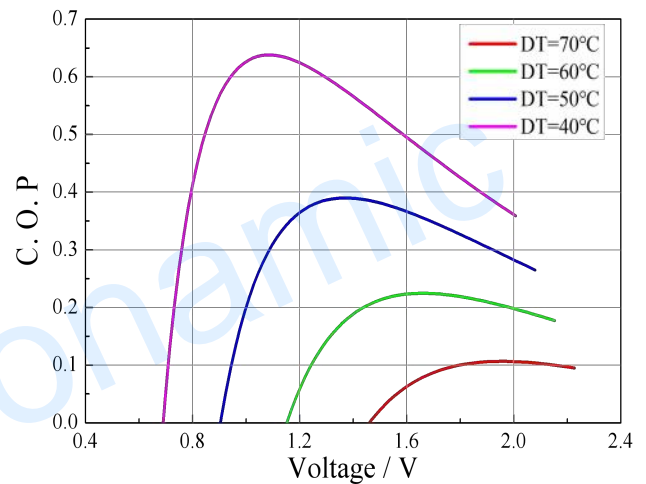
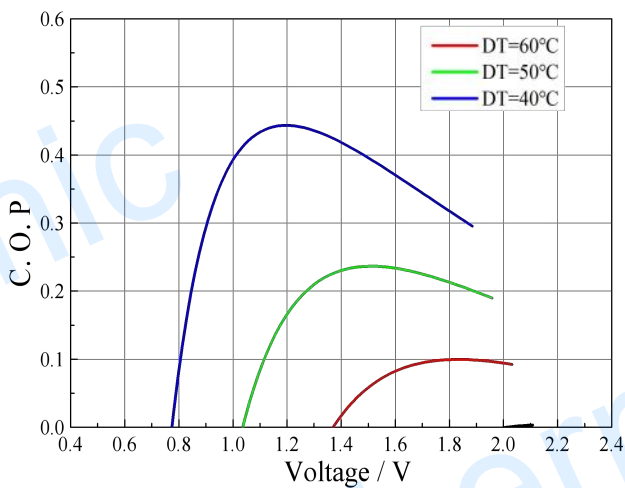
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Performance Curves at Th=27 °C

Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Caution

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.